

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5948963

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
MIDCAP FINANCIAL TRUST	02/03/2020

RECEIVING PARTY DATA

Name:	MICROSS ADVANCED INTERCONNECT TECHNOLOGY LLC
Street Address:	3021 E. CORNWALLIS ROAD
City:	DURHAM
State/Country:	NORTH CAROLINA
Postal Code:	27709

PROPERTY NUMBERS Total: 46

Property Type	Number
Patent Number:	7026602
Patent Number:	6924921
Patent Number:	6752868
Patent Number:	8198974
Patent Number:	8486765
Patent Number:	8035223
Patent Number:	7706152
Patent Number:	8975753
Patent Number:	8008134
Patent Number:	7709966
Patent Number:	8404585
Patent Number:	7999388
Patent Number:	8129834
Patent Number:	8222086
Patent Number:	7944041
Patent Number:	7831874
Patent Number:	7764498
Patent Number:	7719844
Patent Number:	7829994
Patent Number:	8361901

PATENT

Property Type	Number
Patent Number:	9022649
Patent Number:	7978029
Patent Number:	8671560
Patent Number:	8541884
Patent Number:	9257335
Patent Number:	6057520
Patent Number:	6236491
Patent Number:	6972889
Patent Number:	6233088
Patent Number:	6137623
Patent Number:	6456420
Patent Number:	6271150
Patent Number:	6396620
Patent Number:	6731492
Patent Number:	6373682
Patent Number:	6377438
Patent Number:	7042306
Patent Number:	6906598
Patent Number:	6359374
Patent Number:	9437796
Patent Number:	10125599
Patent Number:	9576889
Patent Number:	9881905
Patent Number:	10209175
Application Number:	14359817
Application Number:	14167188

CORRESPONDENCE DATA

Fax Number: (804)344-7999

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ATTORNEY DOCKET NUMBER: 076200.0000036

NAME OF SUBMITTER: DAVID E. BAKER

SIGNATURE:	/David E. Baker/
DATE SIGNED:	02/06/2020
Total Attachments: 8 source=ReleasePatentSecurityAgreementMicros#page1.tif source=ReleasePatentSecurityAgreementMicros#page2.tif source=ReleasePatentSecurityAgreementMicros#page3.tif source=ReleasePatentSecurityAgreementMicros#page4.tif source=ReleasePatentSecurityAgreementMicros#page5.tif source=ReleasePatentSecurityAgreementMicros#page6.tif source=ReleasePatentSecurityAgreementMicros#page7.tif source=ReleasePatentSecurityAgreementMicros#page8.tif	

RELEASE OF PATENT SECURITY INTEREST

This RELEASE OF PATENT SECURITY INTEREST, effective as of February 3, 2020, is made by **MIDCAP FINANCIAL TRUST**, as administrative agent (the "Secured Party"), in favor of **MICROSS ADVANCED INTERCONNECT TECHNOLOGY LLC**, a Delaware limited liability company ("Debtor"), with an address of 3021 E. Cornwallis Road, Durham, NC 27709.

WHEREAS, pursuant to that certain Credit and Guaranty Agreement, dated as of August 7, 2017 (as may have been amended from time to time, the "Credit Agreement") and the Patent Security Agreement dated August 7, 2017 (the "Patent Security Agreement"), Debtor granted to Secured Party a continuing security interest in all of Debtor's right, title and interest in, to and under all Patent Collateral (as defined in the Patent Security Agreement), including, without limitation, the patents and patent applications listed in Schedule A.

WHEREAS, the Patent Security Agreement was recorded in the United States Patent and Trademark Office on August 7, 2017, at Reel 043476 and Frame 0302.

WHEREAS, the Secured Party has agreed to terminate and release its security interest in the Patent Collateral.

NOW, THEREFORE, for valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the Secured Party hereby terminates and releases all liens and security interests in the Patent Collateral, including, without limitation, the patents and patent applications listed in Schedule A, and any patents or patent applications claiming priority thereto granted to the Secured Party by the Debtor.

THIS RELEASE OF PATENT SECURITY INTEREST SHALL BE GOVERNED BY, AND SHALL BE CONSTRUED AND ENFORCED IN ACCORDANCE WITH, THE LAWS OF THE STATE OF NEW YORK, WITHOUT REGARD TO CONFLICTS OF LAWS PRINCIPLES OTHER THAN SECTION 5-1401 AND 5-1402 OF THE NEW YORK GENERAL OBLIGATIONS LAW.

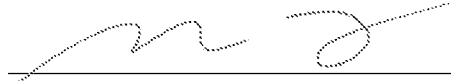
[Signature page follows]

IN WITNESS WHEREOF, the Secured Party has caused this Release of Patent Security Interest to be duly executed as of the date first set forth above.

MIDCAP FINANCIAL TRUST,
as Administrative Agent

By: Apollo Capital Management, L.P.,
its investment manager

By: Apollo Capital Management GP, LLC,
its general partner

By: 
Name: Maurice Amsellem
Title: Authorized Signatory

Schedule A

REGISTERED PATENTS

Grantor	Country	Title	Registration Number	Issue Date
Micross Advanced Interconnect Technology LLC	US	Electromagnetic Radiation Detectors Having a Micromachined Electrostatic Shutter Device	7,026,602	April 11, 2006
Micross Advanced Interconnect Technology LLC	US	Layered Photonic Crystals	6,924,921	August 2, 2005
Micross Advanced Interconnect Technology LLC	US	Layer-by-Layer Assembly of Photonic Crystals	6,752,868	June 22, 2004
Micross Advanced Interconnect Technology LLC	US	Flexible Electrostatic Actuator	8,198,974	June 12, 2012
Micross Advanced Interconnect Technology LLC	US	Structure and Process for Electrical Interconnect & Thermal Management	8,486,765	July 16, 2013
Micross Advanced Interconnect Technology LLC	US	Structure and Process for Electrical Interconnect and Thermal Management	8,035,223	October 11, 2011
Micross Advanced Interconnect Technology LLC	US	DC DC Converter for Low Voltage Power Source	7,706,152	April 27, 2010
Micross Advanced Interconnect Technology LLC	US	Three Dimensional Interconnect Structure and Method Thereof	8,975,753	March 10, 2015
Micross Advanced Interconnect	US	Large Substrate Structural Vias	8,008,134	August 30, 2011

Grantor	Country	Title	Registration Number	Issue Date
Technology LLC				
Micross Advanced Interconnect Technology LLC	US	Large Substrate Structural Vias	7,709,966	May 4, 2010
Micross Advanced Interconnect Technology LLC	US	Preventing Breakage of Long Metal Signal Conductors on Semiconductor Substrates	8,404,585	March 26, 2013
Micross Advanced Interconnect Technology LLC	US	Preventing Breakage of Long Metal Signal Conductors on Semiconductor Substrates	7,999,388	August 16, 2011
Micross Advanced Interconnect Technology LLC	US	Integral Metal Structure With Conductive Post Portions	8,129,834	March 6, 2012
Micross Advanced Interconnect Technology LLC	US	Integrated Semiconductor Substrate Structure Using Incompatible Processes	8,222,086	July 17, 2012
Micross Advanced Interconnect Technology LLC	US	Integrated Semiconductor Substrate Structure Using Incompatible Processes	7,944,041	May 17, 2011
Micross Advanced Interconnect Technology LLC	US	Local Defect Memories on Semiconductor Substrates In a Stack Computer	7,831,874	November 9, 2010
Micross Advanced Interconnect Technology LLC	US	Comb-Shaped Power Bus Bar Assembly Structure Having Integrated Capacitors	7,764,498	July 27, 2010
Micross Advanced Interconnect Technology LLC	US	Stackable Self-Aligning Insulative Guide Tray for Holding Semiconductor Substrates	7,719,844	May 18, 2010

Grantor	Country	Title	Registration Number	Issue Date
Micross Advanced Interconnect Technology LLC	US	Semiconductor Substrate Elastomeric Stack	7,829,994	November 9, 2010
Micross Advanced Interconnect Technology LLC	US	Die Bonding Utilizing a Patterned Adhesion Layer	8,361,901	January 29, 2013
Micross Advanced Interconnect Technology LLC	US	Fluorescence Based Thermometry	9,022,649	May 5, 2015
Micross Advanced Interconnect Technology LLC	US	Multiple-Layer Signal Conductor	7,978,029	July 12, 2011
Micross Advanced Interconnect Technology LLC	US	In System Reflow of Low Temperature Eutectic Bond Balls	8,671,560	March 18, 2014
Micross Advanced Interconnect Technology LLC	US	Through-Substrate Via Having a Strip-Shaped Through-Hole Signal	8,541,884	September 24, 2013
Micross Advanced Interconnect Technology LLC	US	Electronic Devices Utilizing Contact Pads with Protrusions and Methods for Fabrication	9,257,335	February 9, 2016
Micross Advanced Interconnect Technology LLC	US	Arc Resistant High Voltage Micromachined Electronic Switch	6,057,520	May 2, 2000
Micross Advanced Interconnect Technology LLC	US	Micromachined Electrostatic Actuator with Air Gap	6,236,491	May 22, 2001
Micross Advanced Interconnect Technology LLC	US	MEMS Electrostatically Actuated Optical Display Device and Associated Arrays	6,972,889	December 6, 2005
Micross Advanced Interconnect Technology LLC	US	Methods for Modulating a Radiation Signal	6,233,088	May 15, 2001
Micross Advanced Interconnect Technology LLC	US	Modulatable Reflectors and Methods for Using Same	6,137,623	October 24, 2000
Micross Advanced Interconnect Technology LLC	US	Microelectromechanical Elevating Structures	6,456,420	September 24, 2002

Grantor	Country	Title	Registration Number	Issue Date
Micross Advanced Interconnect Technology LLC	US	Methods of Raising Reflow Temperature of Glass Alloys by Thermal Treatment in Steam, and Microelectronic Structures Formed Thereby	6,271,150	August 7, 2001
Micross Advanced Interconnect Technology LLC	US	Electrostatically Actuated Electromagnetic Radiation Shutter	6,396,620	May 28, 2002
Micross Advanced Interconnect Technology LLC	US	Overdrive Structures for Flexible Electrostatic Switch	6,731,492	May 4, 2004
Micross Advanced Interconnect Technology LLC	US	Electrostatically Controlled Variable Capacitor	6,373,682	April 16, 2002
Micross Advanced Interconnect Technology LLC	US	Hybrid Microelectromechanical System Tunable Capacitor and Associated Fabrication Methods	6,377,438	April 23, 2002
Micross Advanced Interconnect Technology LLC	US	Three Dimensional Multi-Mode and Optical Coupling Devices	7,042,306	May 9, 2006
Micross Advanced Interconnect Technology LLC	US	Three Dimensional Multimode and Optical Coupling Devices	6,906,598	June 14, 2005
Micross Advanced Interconnect Technology LLC	US	Miniature Electrical Relays Using a Piezoelectric Thin Film as an Actuating Element	6,359,374	March 19, 2002

Grantor	Country	Title	Registration Number	Issue Date
Micross Advanced Interconnect Technology LLC	US	Rare Earth-Doped Materials With Enhanced Thermoelectric Figure of Merit	9,437,796	September 6, 2016
Micross Advanced Interconnect Technology LLC	US	Location of Sensors in Well Formations	10,125,599	November 13, 2018
Micross Advanced Interconnect Technology LLC	US	Three- Dimensional Electronic Packages Utilizing Unpatterned Adhesive Layer	9,576,889	February 21, 2017
Micross Advanced Interconnect Technology LLC	US	Electronic Packages with Three- Dimensional Conductive Planes, and Methods for Fabrication	9,881,905	January 30, 2018
Micross Advanced Interconnect Technology LLC	US	Detection of Corrosion Using Dispersed Embedded Sensors	10,209,175	February 19, 2019

I. PATENT APPLICATIONS

Grantor	Country	Title	Application Number	Filing Date
Micross Advanced Interconnect Technology LLC	US	Nanoparticle Compact Materials for Thermoelectric Application	14/359,817	May 21, 2014

Micross Advanced Interconnect Technology LLC	US	In System Reflow of Low Temperature Eutectic Bond Balls	14/167,188	January 29, 2014
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